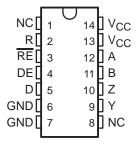
- **Qualified for Automotive Applications**
- **Designed for High-Speed Multipoint Data Transmission Over Long Cables**
- **Operate With Pulse Durations as Low** as 30 ns
- Low Supply Current . . . 5 mA Max
- Meet or Exceed the Requirements of ANSI Standard RS-485 and ISO 8482:1987(E)
- 3-State Outputs for Party-Line Buses
- Common-Mode Voltage Range of -7 V to 12 V
- **Thermal Shutdown Protection Prevents Driver Damage From Bus Contention**
- **Positive and Negative Output Current** Limiting
- Pin Compatible With the SN75ALS180

description

The SN65LBC180 differential driver and receiver pair is a monolithic integrated circuit designed for bidirectional data communication over long cables that take on the characteristics of transmission lines. It is a balanced, or differential, voltage mode device that meets or exceeds the requirements of industry standards ANSI RS-485 and ISO 8482:1987(E). The device is designed using TI's proprietary LinBiCMOS™ with the low power consumption of CMOS and the precision and robustness of bipolar transistors in the same circuit.

The SN65LBC180 combines a differential line driver and receiver with 3-state outputs and operates from a single 5-V supply. The driver and receiver have active-high and active-low enables. respectively, which can be externally connected to function as a direction control. The driver differential outputs and the receiver differential inputs are connected to separate terminals for full-duplex operation and are designed to present minimum loading to the bus whether disabled or powered off ($V_{CC} = 0$). This part features a wide common-mode voltage range making it suitable for point-to-point or multipoint applications.

D PACKAGE (TOP VIEW)



NC-No internal connection

Function Tables

DRIVER

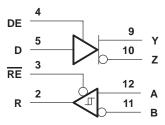
INPUT	ENABLE	OUTPUTS
D	DE	ΥZ
Н	Н	H L
L	Н	L H
X	L	Z Z

RECEIVER

DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
V _{ID} ≤ − 0.2 V	L	L
X	Н	Z
Open circuit	L	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinBiCMOS is a trademark of Texas Instruments Incorporated



SN65LBC180-Q1 LOW-POWER DIFFERENTIAL LINE DRIVER AND RECEIVER PAIR

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description/ordering information (continued)

ORDERING INFORMATION†

TA	PACKA	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC - D	Tape and reel	SN65LBC180IDRQ1	LBC180Q1

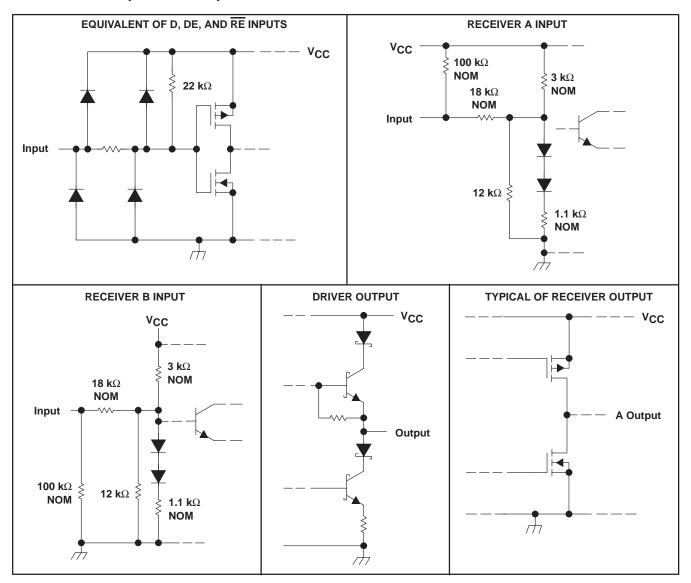
[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

The devices also provide positive and negative output-current limiting and thermal shutdown for protection from line fault conditions. The line driver shuts down at a junction temperature of approximately 172°C.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

schematics of inputs and outputs



SN65LBC180-Q1 LOW-POWER DIFFERENTIAL LINE DRIVER AND RECEIVER PAIR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 7 V
Input voltage range, V _I (A, B)(see Note 1)	–10 V to 15 V
Voltage range at D, R, DE, RE (see Note 1)	\dots -0.3 V to V _{CC} + 0.5 V
Continuous total power dissipation (see Note 2)	Internally limited
Total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{$\Delta$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, V _{IH}	D, DE, and RE	2			V
Low-level input voltage, V _{IL}	D, DE, and RE			8.0	V
Differential input voltage, $V_{\mbox{\scriptsize ID}}$		-6‡		6	V
Voltage at any bus terminal (separately or common mode), VO, VI, or VIC	A, B, Y, or Z	_7 [‡]		12	V
	Y or Z			-60	
High-level output current, IOH	R			-8	mA
	Y or Z			60	
Low-level output current, IOL	R			8	mA
Operating free-air temperature, T _A	-40		85	°C	

[‡] The algebraic convention where the least positive (more negative) limit is designated minimum, is used in this data sheet for the differential input voltage, voltage at any bus terminal, operating temperature, input threshold voltage, and common-mode output voltage.



^{2.} The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.

DRIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	MIN	TYP [†]	MAX	UNIT
VIK	Input clamp voltage	$I_{I} = -18 \text{ mA}$				-1.5	V
137	Differential output voltage magnitude	R _L = 54 Ω,	See Figure 1	1.1	2.5	5	.,
VOD	(see Note 3)	R _L = 60 Ω,	See Figure 2	1.1	2	5	V
Δ V _{OD} Change in magnitude of differential output voltage (see Note 4)		See Figures 1 and	2			±0.2	V
Voc	Common-mode output voltage			1	2.5	3	V
Δ V _{OC}	Change in magnitude of common-mode output voltage (see Note 4)	$R_L = 54 \Omega$,	See Figure 1			±0.2	V
IO	Output current with power off	$V_{CC} = 0$,	$V_0 = -7 \text{ V to } 12 \text{ V}$			±100	μΑ
loz	High-impedance-state output current	$V_0 = -7 \text{ V to } 12 \text{ V}$				±100	μΑ
lн	High-level input current	V _I = 2.4 V				-100	μΑ
I _I L	Low-level input current	V _I = 0.4 V				-100	μΑ
los	Short-circuit output current	-7 V ≤ V _O ≤ 12 V				±250	mA
laa	Cumply ourront	Receiver disabled	Outputs enabled			5	mA
ICC	Supply current	Receiver disabled	Outputs disabled			3	IIIA

† All typical values are at V_{CC} = 5 V and T_A = 25°C. NOTES: 3. The minimum V_{OD} specification of the SN65LBC180 may not fully comply with ANSI RS-485 at operating temperatures below 0°C. System designers should take the possibly lower output signal into account in determining the maximum signal-transmission

4. $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in the steady-state magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
td(OD)	Differential output delay time	D 540	0	7	12	18	ns
t _t (OD)	Differential output transition time	$R_L = 54 \Omega$,	See Figure 3	5	10	20	ns
^t PZH	Output enable time to high level	$R_L = 110 \Omega$,	See Figure 4			35	ns
tPZL	Output enable time to low level	$R_L = 110 \Omega$,	See Figure 5			35	ns
^t PHZ	Output disable time from high level	$R_L = 110 \Omega$,	See Figure 4			50	ns
tPLZ	Output disable time from low level	$R_L = 110 \Omega$,	See Figure 5			35	ns

RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CON	MIN	TYP	MAX	UNIT	
V _{IT+}	Positive-going input threshold voltage	$I_O = -8 \text{ mA}$				0.2	V
V_{IT-}	Negative-going input threshold voltage	$I_O = 8 \text{ mA}$		-0.2			V
V _{hys}	Hysteresis voltage (V _{IT+} - V _{IT-})				45		mV
٧IK	Enable-input clamp voltage	I _I = –18 mA				-1.5	V
Vон	High-level output voltage	V _{ID} = 200 mV,	I _{OH} = -8 mA	3.5	4.5		V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	I _{OL} = 8 mA		0.3	0.5	V
loz	High-impedance-state output current	$V_O = 0 V \text{ to } V_{CC}$				±20	μΑ
lιΗ	High-level enable-input current	V _{IH} = 2.4 V				-50	μΑ
Ι _Ι L	Low-level enable-input current	V _{IL} = 0.4 V				-100	μΑ
		V _I = 12 V, Other input at 0 V	$V_{CC} = 5 V$,		0.7	1	
	Bus input current	V _I = 12 V, Other input at 0 V	V _{CC} = 0 V,		0.8	1	
i _l		$V_I = -7 \text{ V},$ Other input at 0 V	V _{CC} = 5 V,		-0.5	-0.8	mA
		V _I = -7 V, Other input at 0 V	V _C C = 0 V,		-0.5	-0.8	
	Complex surrount	Duiven disabled	Outputs enabled			5	^
ICC	Supply current	Driver disabled	Outputs disabled			3	mA

switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
tPHL	Propagation delay time, high- to low-level output		11	22	33	ns	
tPLH	Propagation delay time, low- to high-level output	V 45V/245V 0275			22	33	ns
tsk(p)	Pulse skew (tpHL - tpLH)	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$ See Figure 6			3	6	ns
t _t	Transition time				5	8	ns
^t PZH	Output enable time to high level					35	ns
tPZL	Output enable time to low level	See Figure 7				30	ns
^t PHZ	Output disable time from high level	See Figure /				35	ns
tPLZ	Output disable time from low level				30	ns	



PARAMETER MEASUREMENT INFORMATION

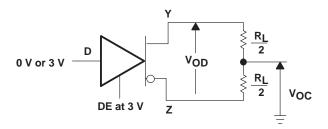


Figure 1. Differential and Common-Mode Output Voltages

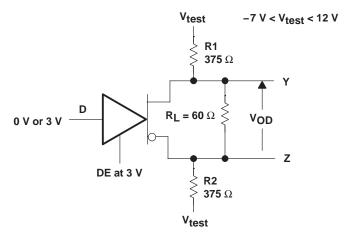
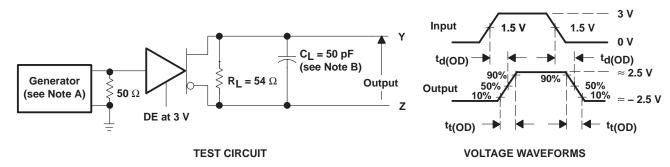


Figure 2. Driver V_{OD} Test Circuit



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR > 1 MHz, 50% duty cycle, $t_f \le 6$ ns, $t_f \le$

B. CL includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Differential Output Delay and Transition Time Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

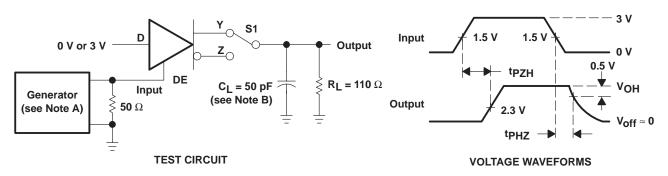


Figure 4. Driver Test Circuit and Enable and Disable Time Waveforms

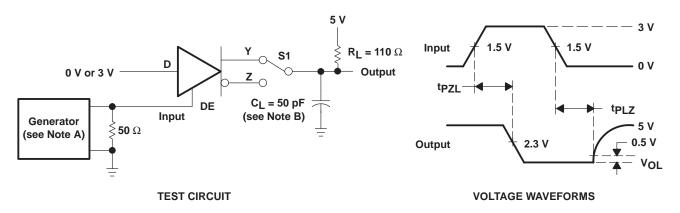
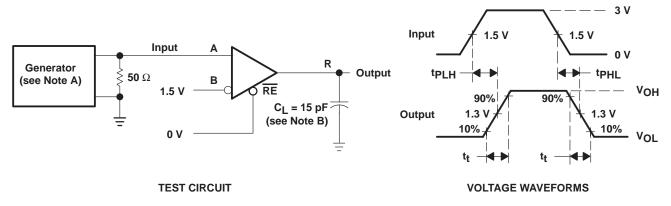


Figure 5. Driver Test Circuit and Enable and Disable Time Voltage Waveforms



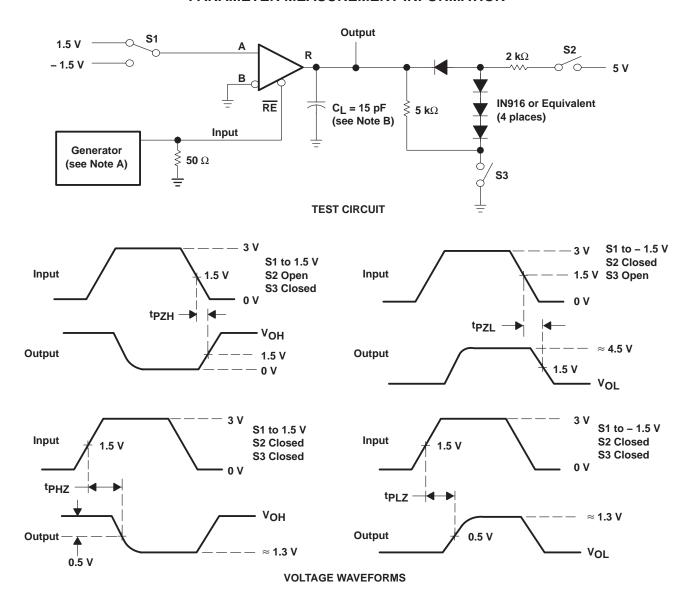
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. C_L includes probe and jig capacitance.

Figure 6. Receiver Test Circuit and Propagation Delay Time Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\text{f}} \leq$ 6 ns, $t_{\text{f}} \leq$ 7 ns, $t_{\text{f}} \leq$ 8 ns, $t_{\text{f}} \leq$ 9 ns, $t_{$

B. C_L includes probe and jig capacitance.

Figure 7. Receiver Output Enable and Disable Times

TYPICAL CHARACTERISTICS

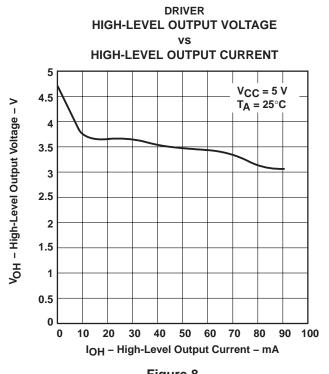


Figure 8

DRIVER

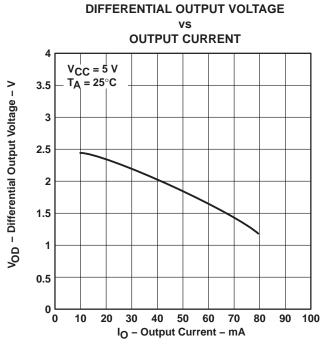
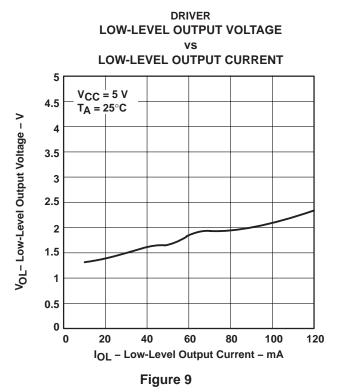
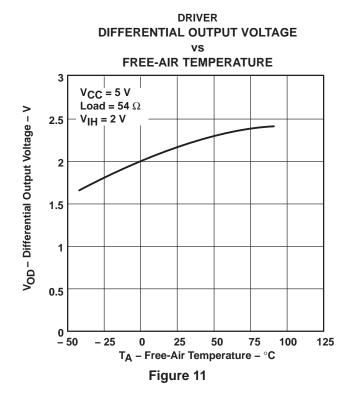


Figure 10



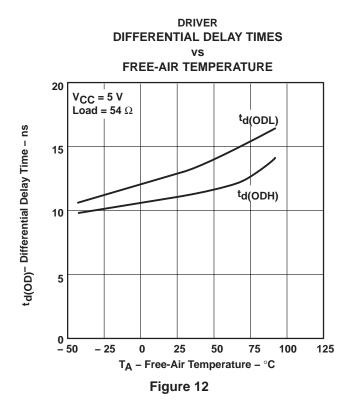




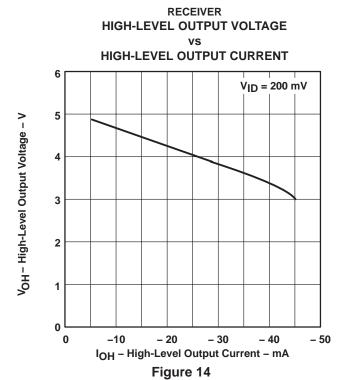
DRIVER

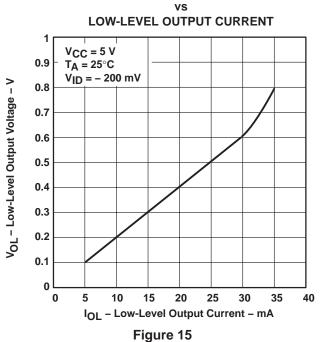
OUTPUT CURRENT

TYPICAL CHARACTERISTICS



vs **SUPPLY VOLTAGE** 80 $R_L = 54 \Omega$ 60 loL 40 Io - Output Current - mA 20 0 -20 -40IOH -60 -80 0 3 5 6 V_{CC} - Supply Voltage - V Figure 13





RECEIVER

LOW-LEVEL OUTPUT VOLTAGE

TYPICAL CHARACTERISTICS

60

55

50

45

40 35

30

25 20

> > 10 k

ICC - Average Supply Current - mA

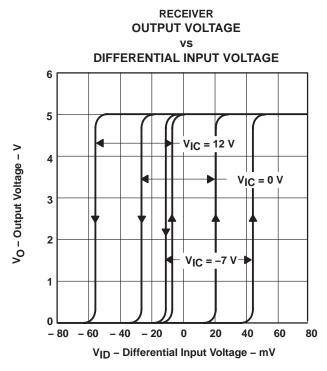


Figure 16

RECEIVER

BUS INPUT CURRENT INPUT VOLTAGE (COMPLEMENTARY INPUT AT 0 V) T_A = 25°C VCC = 5 V 8.0 0.6 - Bus Input Current - mA 0.4 0.2 0 - 0.2 -0.4- 0.6 - 0.8 The shaded region of this graph represents more than 1 unit load per RS-485. - 8 -6 -4 0 2 - 2 6 8 10 12 V_I - Input Voltage - V

Figure 18

AVERAGE SUPPLY CURRENT FREQUENCY $T_A = 25^{\circ}C$ $V_{CC} = 5 V$ **DRVR and RCVR Enabled** Driver Load = Receiver Inputs Receiver Load = 50 pF

Figure 17

1 M

f - Frequency - Hz

10 M

100 M

100 k

RECEIVER PROPAGATION DELAY TIME FREE-AIR TEMPERATURE

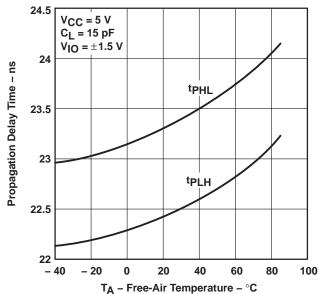
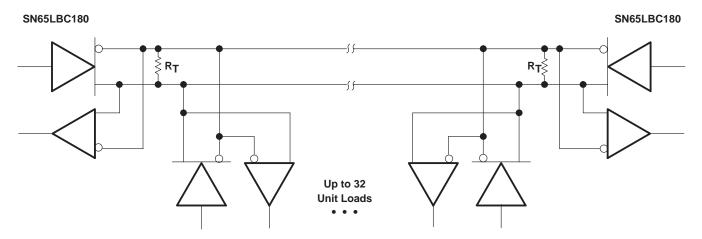


Figure 19

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APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible. One SN65LBC180 typically represents less than one unit load.

Figure 20. Typical Application Circuit



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PACKAGING INFORMATION

Ordera	able Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN65LBC	C180IDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BL180Q1	Samples
SN65LE	3C180IDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LBC180IQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF SN65LBC180-Q1:

Catalog: SN65LBC180





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NOTE: Qualified Version Definitions:

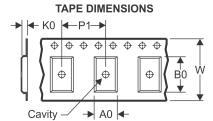
Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Mar-2013

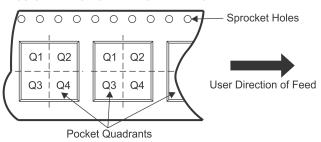
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC180IDRG4Q1	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

www.ti.com 14-Mar-2013



*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN65LBC180IDRG4Q1	SOIC	D	14	2500	367.0	367.0	38.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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